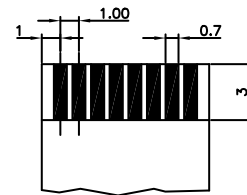
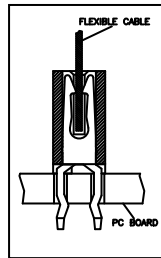
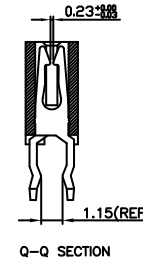
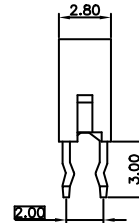
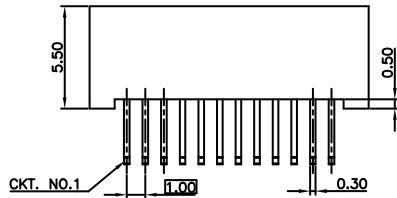
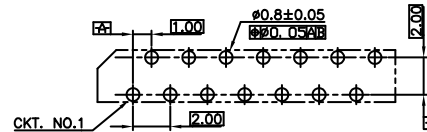


DIM A=1mm*(CKT-1)
 DIM B=DIM A+2.1mm
 DIM C=DIM A+4mm



FFC/FPC DIMENSION
 THICKNESS 0.25 ~ 0.32mm
 TOLERANCE: 0.05mm



PCB Board Layout
 Component Side
 PCB T = 0.6mm

ELECTRICAL:

CURRENT RATING: 0.5A
 CONTACT RESISTANCE:
 < 30 Milliohm Max.
 INSULATION RESISTANCE:
 > 100Megaohm Min.
 DIELECTRIC WITHSTANDING VOLTAGE:
 50 V (rms) AC for 1 Minute
 OPERATING TEMPERATURE: -40°C to + 105°C

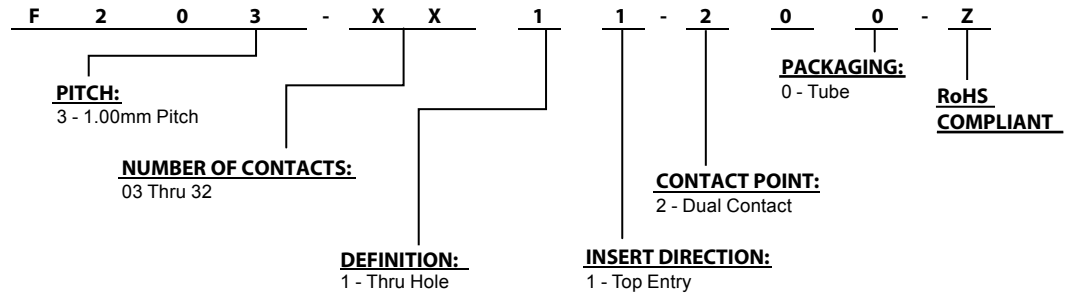
MATERIAL:

INSULATOR: Thermoplastic, Nylon 46
 FLAMMABILITY RATING: UL 94V-0
 CONTACT MATERIAL: Copper Alloy
 PLATING: Tin Plating Over Nickel

SOLDERABILITY:

PER MIL-STD-202F Method 208D

HOW TO ORDER:



| Rev | Drawn | Checked | Approved | Date | |
|-----------|-------------|--------------|---------------|--------------|---|
| 0 | Issued | B.S. | S.M. | S.M. | 03/01/07 |
| | | | | | SMP TECHNOLOGY, INC. |
| | | | | | FFC Connector, LIF, Standard, 1.0mm Pitch, Dual Point Contact |
| | | | | | |
| | | | | | |
| TOL. DEC. | .X +/- 0.25 | .XX +/- 0.20 | .XXX +/- 0.10 | ANGLE +/- 2° | UNIT: mm |
| | | | | | P/N: F203-XX11-200-Z |